



LEDTECH ELECTRONICS CORP.

NANYA ROAD, MUGANG ZHAOQING
CITY GUANGDONG CHINA.

TEL: 86-758-2875541, 2870651, 2877464, 2876185, 2877017

FAX: 86-758-2878014

Http://www.ledtech.com.tw

SPECIFICATION

PART NO. : LP30N3-S067

COB 35 x 35mm TYPE



Approved by	Checked by	Prepared by



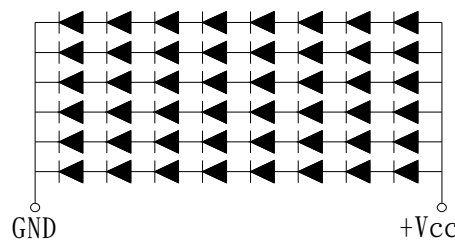
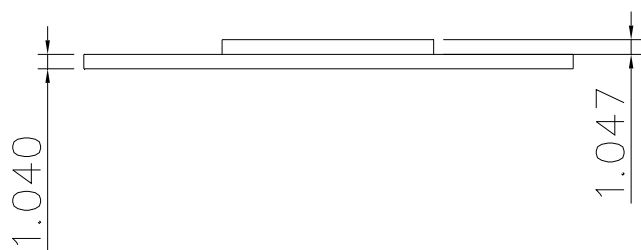
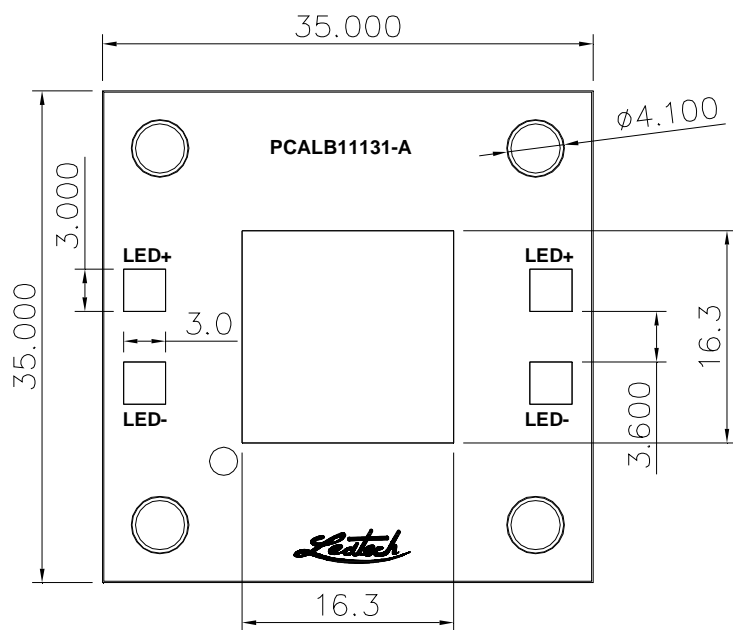
Features

- Pb-Free soldering application
- RoHS compliance
- Multi-Chip package
- High Reliability

Application

- Bay-light module
- Indoor decorative lighting
- Illumination
- Automotive Application
- Architectural Lighting
- Indicator / Decoration

Package Dimensions



Notes:

1. All dimensions are in mm.
2. Tolerance is ± 0.25 mm unless otherwise noted.

Description

Part No.	LED Chip		Lens Color
	Material	Emitting Color	
LP30N3-S067	InGaN/Sapphire	White	Yellow Diffused

Absolute Maximum Ratings at Ta=25 °C

Parameter	Symbol	Rating	Unit
Power Dissipation	P _D	9.8	W
D.C. Forward Current	I _f	350	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	I _f (Peak)	400	mA
Operating Temperature Range	T _{opr.}	-40 to +100	°C
Storage Temperature Range	T _{stg.}	-40 to +100	°C
Solder Heat Resistance	SHR	Hand Soldering:300±5°C for 3 sec.	
Electric Static Discharge Threshold (HBM)	ESD	1000	V

Electrical and Optical Characteristics :

Parameter	Symbol	Condition	Values			Units
			Min.	Typ.	Max.	
Luminous Flux		I _F =350mA		960		lm
	Rank L2		800	--	1000	
	Rank L3		1000	--	1200	
Forward voltage		I _F =350mA		25.3		V
	Rank V2		22	--	25	
	Rank V3		25	--	28	
Correlated Colour Temperature	CCT	I _F =350mA	5250	--	6000	K
CIE Chromaticity Coordinates: X Axis	X	I _F =350mA	--	0.3287	--	
CIE Chromaticity Coordinates: Y Axis	Y	I _F =350mA	--	0.3417	--	
Reverse Current	I _R	V _r =5V	--	--	50	μA
Color Renderig Index	CRI	I _F =350mA	80	--	--	Ra
Viewing angle at 50% IV		2θ _{1/2}	--	120	--	Deg.

Notes:

1. The datas tested by IS tester.
2. Customer's special requirements are also welcome.

Typical Electrical/Optical Characteristic Curves

(25°C Ambient Temperature Unless Otherwise Noted)

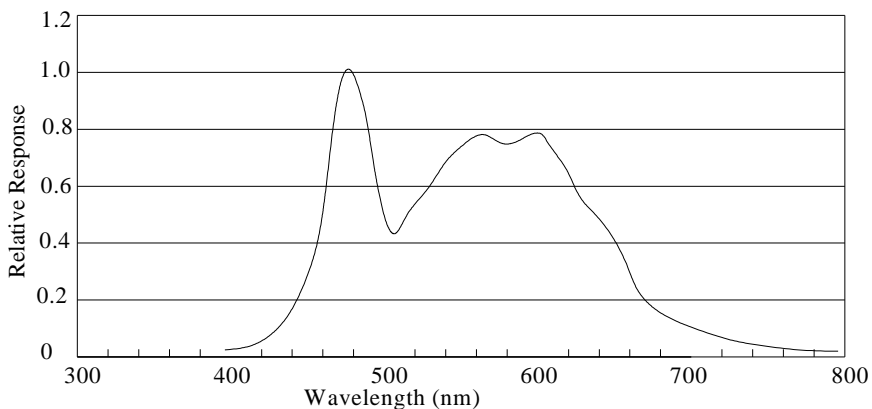
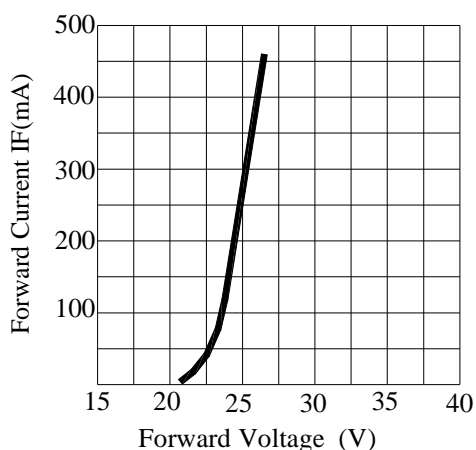
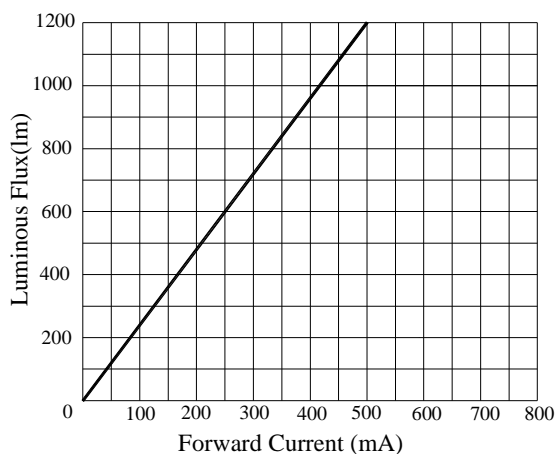


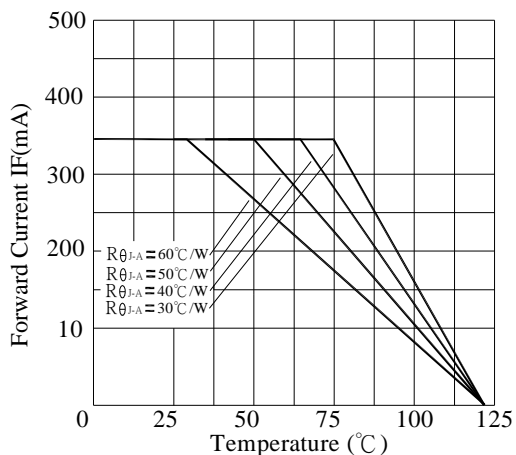
Fig.1 WHITE LED Spectrum VS. WAVELENGTH



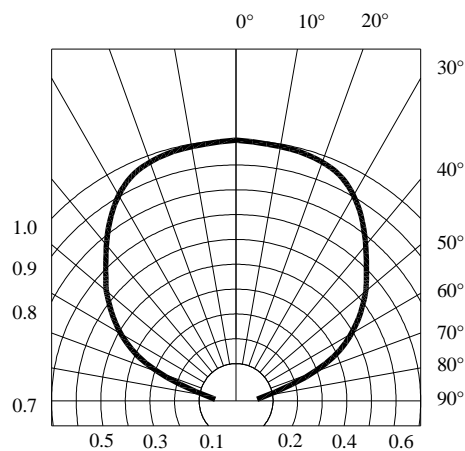
Forward Current VS. Applied Voltage



Forward Current VS. Luminous Intensity



Ambient Temperature VS. Forward Current



Radiation Diagram

Handling of Silicone Resin LEDs

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound



Figure 1

In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

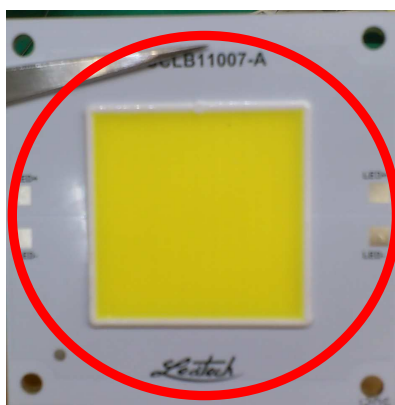
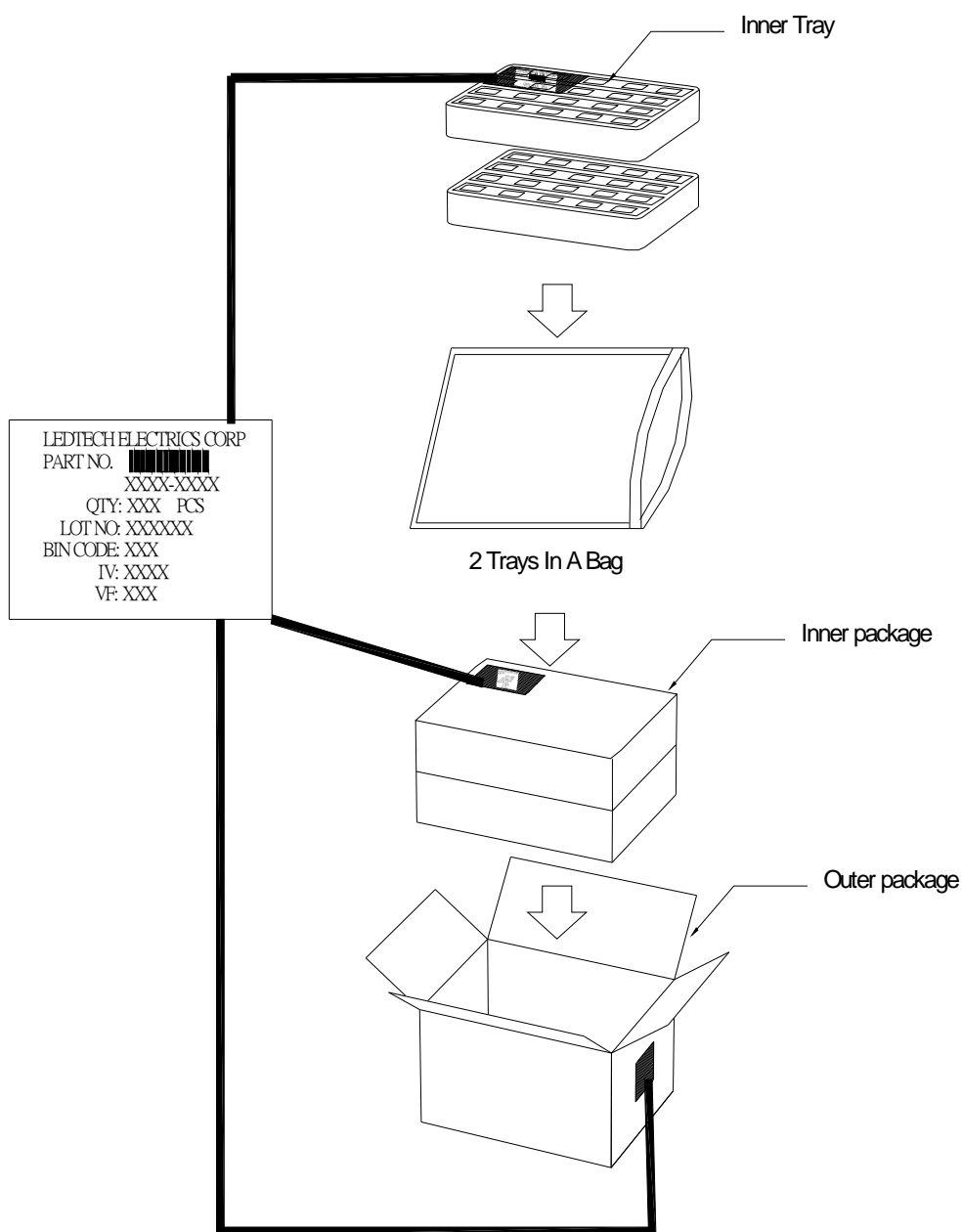


Figure 2

When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented. This is assured by choosing a pick and place nozzle which is larger than the LED's reflector area.

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Packaging :**Notes :**

1. All dimensions are in mm.
2. There are 16pcs in a tray.
3. There are 2 trays in an inner box.
4. There are 2 inner boxes in an outer box.